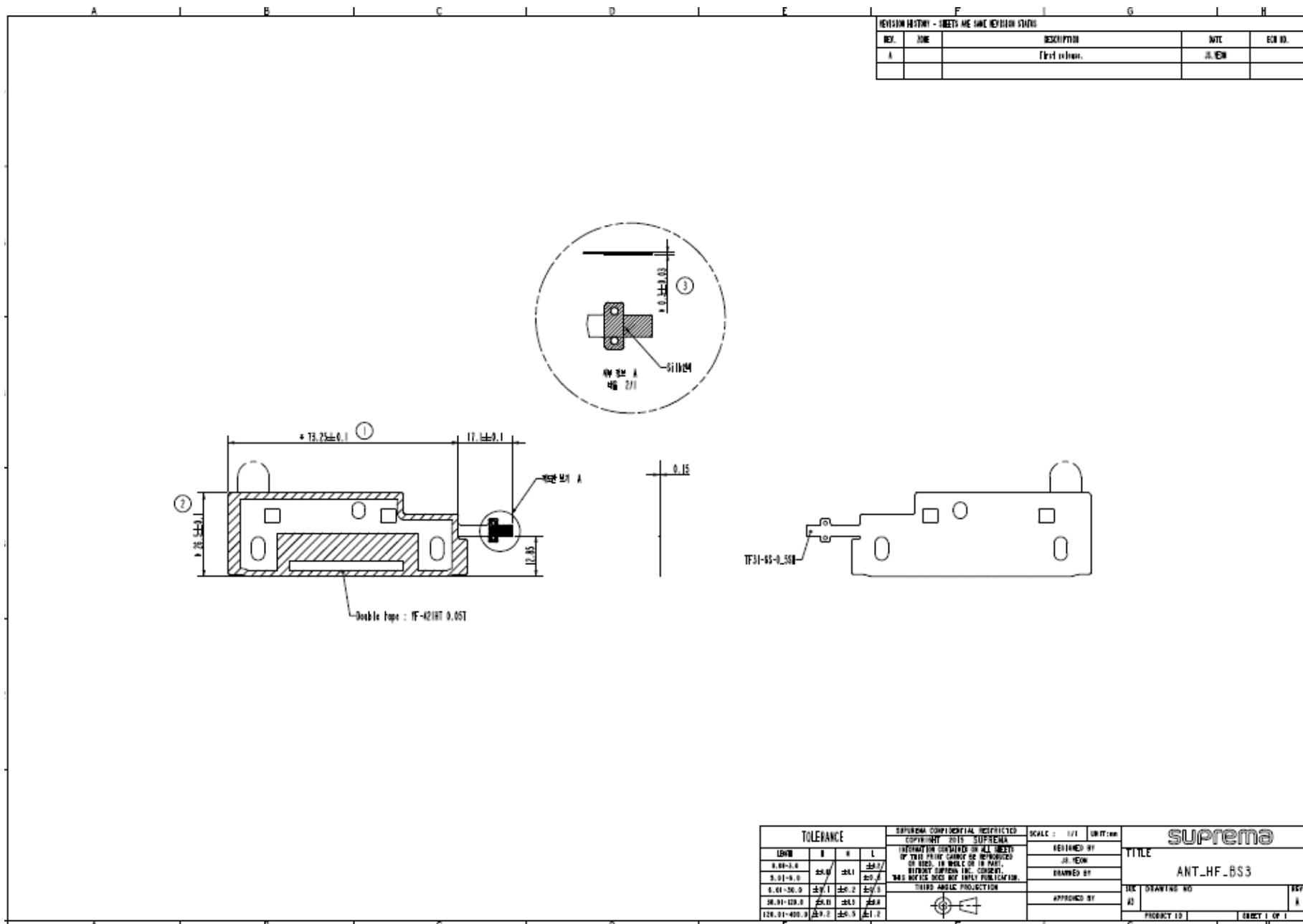
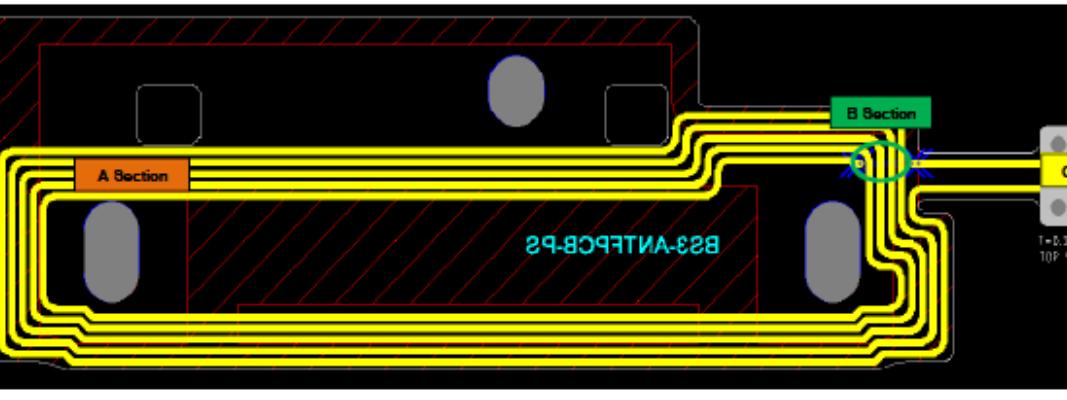


drawing



## Dimention

## F.P.C STRUCTURE (FPCB구조)

Model	BS3 HF_ANT_PS			Layer	DS
					
Layer	Item	Specification	A Section	B Section	C Section
XXX	PAPER	PAPER		125.0	
XXX	TAPE	Adhesive		50.0	
XXX	Kapton	Polyimide		125.0	
		Adhesive		40.0	
C/S	Coverlay	Polyimide	12.5	12.5	12.5
		Adhesive	25.0	25.0	25.0
C/S	Cu Plate	Cu Plate		10.0	
		Copper foil		36.0	
XXX	FCCL	Adhesive	15.0	15.0	15.0
		Polyimide	25.0	25.0	25.0
S/S	Cu Plate	Adhesive	15.0	15.0	15.0
		Copper foil	36.0	36.0	36.0
S/S	Coverlay	Cu Plate	10.0	10.0	10.0
		Adhesive	25.0	25.0	
		Polyimide	12.5	12.5	
LAYER		1	2	1	
Total Thickness		176.00	272.00	303.50	
Tolerance				0.3T±0.03	
※ PAPER 두께 제외					NT: 3-7um, Au: MIN 0.03um
					서울화학
					무전해 금 도금
					표면처리